

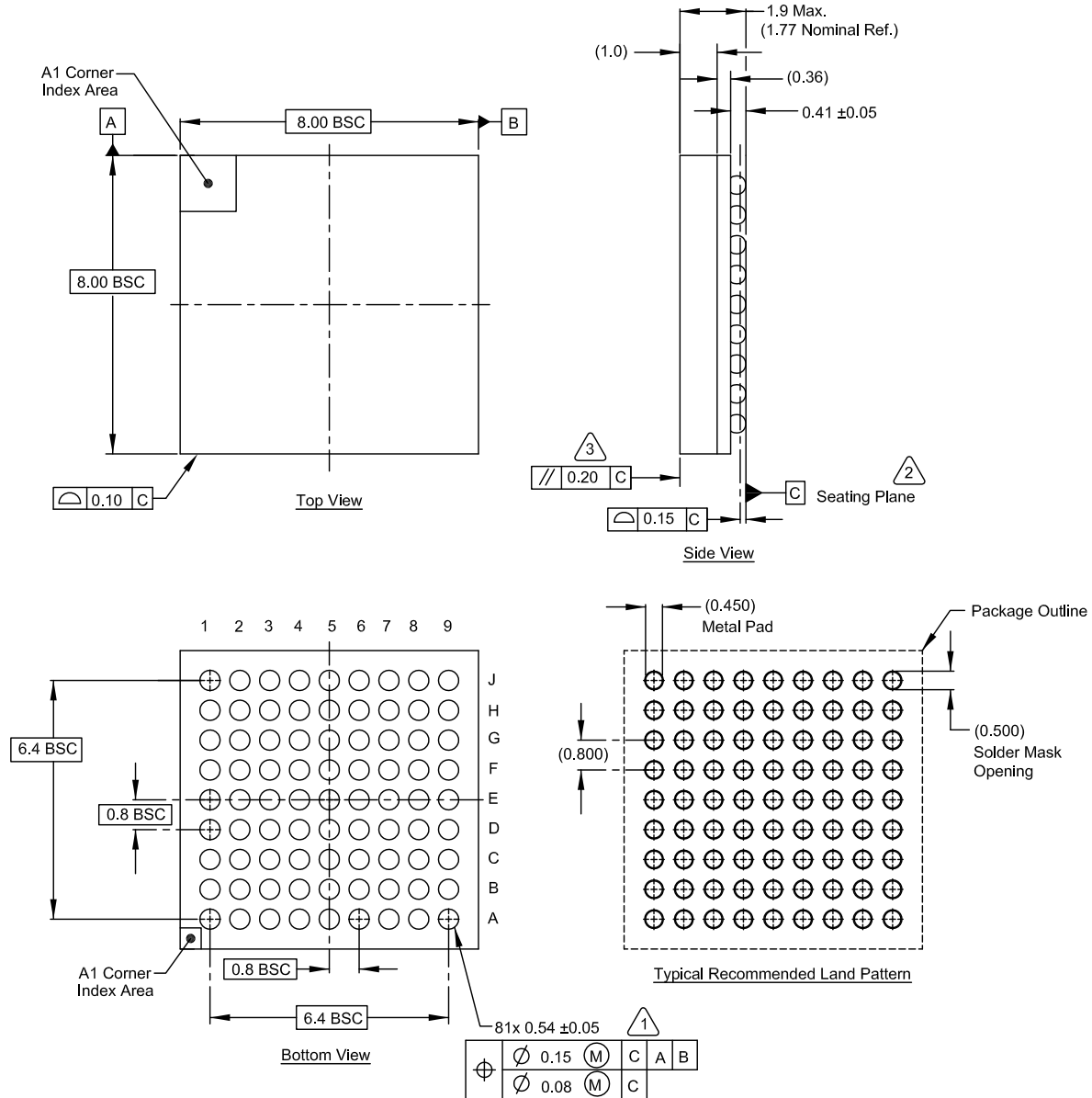
Plastic Packages for Integrated Circuits

Package Outline Drawing

V81.8x8

81 Ball Plastic Ball Grid Array Package

Rev 0, 10/18



Notes:

- ① Dimension is measured at the maximum solder ball diameter, parallel to primary datum [C].
- ② Datum [C] (seating plane) is defined by the spherical crowns of the solder balls.
- ③ Parallelism measurement shall exclude any effect of the mark on the top surface of the package.
4. All dimensions and tolerances conform to ASME Y14.5M.
5. Units: mm